Hae Do Jeong

List of Publications by Year
in descending order

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32	335	686830 13	839053 18
papers	citations	h-index	g-index

32	32	32	155
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Approaches to Sustainability in Chemical Mechanical Polishing (CMP): A Review. International Journal of Precision Engineering and Manufacturing - Green Technology, 2022, 9, 349-367.	2.7	34
2	Mechanical effect of process condition and abrasive concentration on material removal rate profile in copper chemical mechanical planarization. Journal of Materials Processing Technology, 2009, 209, 1729-1735.	3.1	26
3	Effect of pad groove geometry on material removal characteristics in chemical mechanical polishing. International Journal of Precision Engineering and Manufacturing, 2012, 13, 303-306.	1.1	24
4	Heat and its effects to chemical mechanical polishing. Journal of Materials Processing Technology, 2006, 178, 82-87.	3.1	23
5	Evaluation of environmental impacts during chemical mechanical polishing (CMP) for sustainable manufacturing. Journal of Mechanical Science and Technology, 2013, 27, 511-518.	0.7	20
6	Effect of surfactant on package substrate in chemical mechanical planarization. International Journal of Precision Engineering and Manufacturing - Green Technology, 2015, 2, 59-63.	2.7	20
7	Effect of non-spherical colloidal silica particles on removal rate in oxide CMP. International Journal of Precision Engineering and Manufacturing, 2015, 16, 2611-2616.	1.1	19
8	Development of green CMP by slurry reduction through controlling platen coolant temperature. International Journal of Precision Engineering and Manufacturing - Green Technology, 2015, 2, 339-344.	2.7	19
9	Effect of glycine on copper CMP. International Journal of Precision Engineering and Manufacturing - Green Technology, 2016, 3, 155-159.	2.7	19
10	The effects of a spray slurry nozzle on copper CMP for reduction in slurry consumption. Journal of Mechanical Science and Technology, 2015, 29, 5057-5062.	0.7	18
11	Kinematical Modeling of Pad Profile Variation during Conditioning in Chemical Mechanical Polishing. Japanese Journal of Applied Physics, 2009, 48, 126502.	0.8	15
12	Effect of diluted colloidal silica slurry mixed with ceria abrasives on CMP characteristic. International Journal of Precision Engineering and Manufacturing - Green Technology, 2016, 3, 13-17.	2.7	15
13	Preliminary study on the effect of spray slurry nozzle in CMP for environmental sustainability. International Journal of Precision Engineering and Manufacturing, 2014, 15, 995-1000.	1.1	13
14	Effect of Relative Surface Charge of Colloidal Silica and Sapphire on Removal Rate in Chemical Mechanical Polishing. International Journal of Precision Engineering and Manufacturing - Green Technology, 2019, 6, 339-347.	2.7	13
15	Analysis of Correlation between Pad Temperature and Asperity Angle in Chemical Mechanical Planarization. Applied Sciences (Switzerland), 2021, 11, 1507.	1.3	11
16	Numerical and Experimental Study of Air-to-Air Plate Heat Exchangers with Plain and Offset Strip Fin Shapes. Energies, 2020, 13, 5710.	1.6	8
17	Effect of Ceria Abrasives on Planarization Efficiency in STI CMP Process. ECS Transactions, 2009, 19, 51-59.	0.3	6
18	Development of intelligent pad monitoring system and application to analysis of pressure distribution in chemical mechanical polishing process. International Journal of Precision Engineering and Manufacturing, 2014, 15, 2005-2009.	1.1	5

#	Article	IF	Citations
19	Wafer size effect on material removal rate in copper CMP process. Journal of Mechanical Science and Technology, 2017, 31, 2961-2964.	0.7	4
20	Chemical mechanical planarization of advanced package substrate by controlling selectivity of copper to polymer. Journal of Mechanical Science and Technology, 2018, 32, 3843-3848.	0.7	4
21	Surface Activation by Electrolytically Ionized Slurry during Cu CMP. ECS Journal of Solid State Science and Technology, 2019, 8, P3053-P3057.	0.9	4
22	Hybrid CMP Slurry Supply System Using Ionization and Atomization. Applied Sciences (Switzerland), 2021, 11, 2217.	1.3	4
23	Reduction of the Maximum Step Height on a Package Substrate by the Optimization of Slurry Chemical Additives. International Journal of Precision Engineering and Manufacturing, 2019, 20, 905-913.	1.1	3
24	Effect of the Lapping Platen Groove Density on the Characteristics of Microabrasive-Based Lapping. Micromachines, 2020, 11, 775.	1.4	2
25	Effect of Hydrogen Peroxide and Oxalic Acid on Material Removal in Al CMP. Journal of the Korean Society for Precision Engineering, 2017, 34, 307-310.	0.1	2
26	Planarization Modeling Based on Contact Mode Between Pad Asperity and Oxide Pattern During CMP. Journal of the Korean Society for Precision Engineering, 2019, 36, 363-372.	0.1	2
27	Material Removal Model for Lapping Process Based on Spiral Groove Density. Applied Sciences (Switzerland), 2021, 11, 3950.	1.3	1
28	Finite Element Analysis on Dynamic Viscoelasticity of CMP Polishing Pad. Journal of the Korean Society for Precision Engineering, 2019, 36, 177-181.	0.1	1
29	Identification of the Break-In Mechanism by Asperity Deformation of CMP Pad. Journal of the Korean Society for Precision Engineering, 2021, 38, 87-95.	0.1	0
30	516 A Study on Fabrication of PDP Barrier Ribs Using Micro Tooling Process. The Proceedings of the JSME Materials and Processing Conference (M&P), 2002, 10.2, 119-124.	0.1	0
31	Planarization Modeling for Device Pattern with Geometric Characteristics of Pad Asperity. Journal of the Korean Society for Precision Engineering, 2020, 37, 567-577.	0.1	0
32	Variation of Pad Temperature Distribution by Slurry Supply Conditions. Journal of the Korean Society for Precision Engineering, 2020, 37, 873-880.	0.1	0